

Photocouplers Photorelay

TLP3109

1. Applications

- · Mechanical relay replacements
- · Security Systems
- · Measuring Instruments
- Factory Automation (FA)
- · Amusement Equipment

2. General

The TLP3109 photorelay consists of a photo MOSFET optically coupled to an infrared light emitting diode. It is housed in a 2.54SOP6 package. The low ON-state resistance and the high permissible ON-state current of the TLP3109 make it suitable for power line control applications.

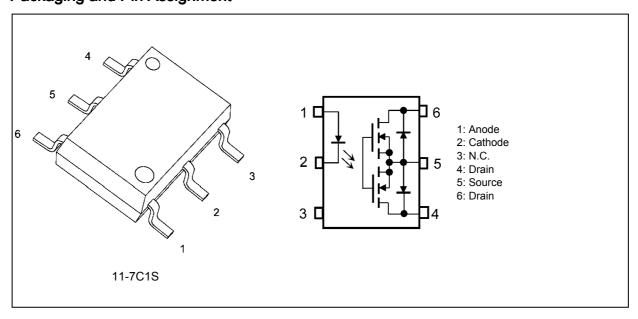
3. Features

- (1) Normally opened (1-Form-A)
- (2) OFF-state output terminal voltage: 100 V (min)
- (3) Trigger LED current: 3 mA (max)
- (4) ON-state current: 2.0 A (max) (A connection)
- (5) ON-state resistance: 70 mΩ (max) (A connection)
- (6) Isolation voltage: 1500 Vrms (min)
- (7) Safety standards

UL-approved: UL1577, File No.E67349

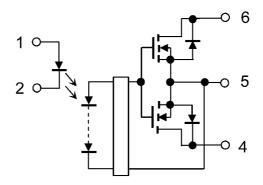
cUL-approved: CSA Component Acceptance Service No.5A File No.E67349

4. Packaging and Pin Assignment





5. Internal Circuit



6. Absolute Maximum Ratings (Note) (Unless otherwise specified, Ta = 25 °C)

	Characteristics		Symbol	Note	Rating	Unit
LED	Input forward current		I _F		30	mA
	Input forward current derating	$(T_a \ge 25 \text{ °C})$	$\Delta I_F/\Delta T_a$		-0.3	mA/°C
	Input forward current (pulsed)	(100 μs pulse, 100 pps)	I _{FP}		1	Α
	Input reverse voltage		V_R		5	V
	Input power dissipation		P_{D}		50	mW
	Input power dissipation derating	$(T_a \ge 25 ^{\circ}C)$	$\Delta P_D/\Delta T_a$		-0.5	mW/°C
	Junction temperature		Tj		125	ů
Detector	OFF-state output terminal voltage		V _{OFF}		100	V
	ON-state current (A connection)		I _{ON}	(Note 1)	2.0	Α
	ON-state current (B connection)		I _{ON}	(Note 1)	2.0	
	ON-state current (C connection)		I _{ON}	(Note 1)	4.0]
	ON-state current derating (A connection)	$(T_a \ge 25 ^{\circ}C)$	Δl _{ON} /ΔT _a	(Note 1)	-20	mA/°C
	ON-state current derating (B connection)	$(T_a \ge 25 ^{\circ}C)$	Δl _{ON} /ΔT _a	(Note 1)	-20	
	ON-state current derating (C connection)	$(T_a \ge 25 \text{ °C})$	Δl _{ON} /ΔT _a	(Note 1)	-40	
	ON-state current (pulsed)	(t = 100 ms, Duty = 1/10)	I _{ONP}		6	Α
	Output power dissipation		Po		400	mW
	Output power dissipation derating	$(T_a \ge 25 \text{ °C})$	$\Delta P_{O}/\Delta T_{a}$		-4.0	mW/°C
	Junction temperature		Tj		125	ů
Common	Storage temperature		T _{stg}		-55 to 125	
	Operating temperature		T _{opr}		-40 to 85	
	Lead soldering temperature	(10 s)	T _{sol}		260	
	Isolation voltage	AC, 60 s, R.H. ≤ 60 %	BV _S	(Note 2)	1500	Vrms

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note 1: For an application circuit example, see Chapter 12.2.

Note 2: This device is considered as a two-terminal device: Pins 1, 2 and 3 are shorted together, and pins 4, 5 and 6 are shorted together.



7. Recommended Operating Conditions (Note)

Characteristics	Symbol	Note	Min	Тур.	Max	Unit
Supply voltage	V_{DD}		_	_	80	V
Input forward current	I _F		5	10	25	mA
ON-state current (A connection)	I _{ON}		_	_	2.0	Α
Operating temperature	T _{opr}		-20		65	°C

Note: The recommended operating conditions are given as a design guide necessary to obtain the intended performance of the device. Each parameter is an independent value. When creating a system design using this device, the electrical characteristics specified in this data sheet should also be considered.

8. Electrical Characteristics (Unless otherwise specified, T_a = 25 °C)

	Characteristics	Symbol	Note	Test Condition	Min	Тур.	Max	Unit
LED	Input forward voltage	V _F		I _F = 10 mA	1.18	1.33	1.48	V
	Input reverse current	I _R		V _R = 5 V			10	μΑ
	Input capacitance	Ct		V = 0 V, f = 1 MHz		70		pF
Detector	OFF-state current	I _{OFF}		V _{OFF} = 100 V	_	_	1	μΑ
				V _{OFF} = 80 V			20	nA
	Output capacitance	C _{OFF}		V = 0 V, f = 1 MHz		500		pF

9. Coupled Electrical Characteristics (Unless otherwise specified, T_a = 25 °C)

Characteristics	Symbol	Note	Test Condition	Min	Тур.	Max	Unit
Trigger LED current	I _{FT}		I _{ON} = 100 mA	_	0.4	3	mA
Return LED current	I _{FC}		I _{OFF} = 10 μA	0.1			
ON-state resistance (A connection)	R _{ON}	(Note 1)	I _{ON} = 2.0 A, I _F = 5 mA, t < 1 s	_	45	70	mΩ
ON-state resistance (B connection)					22	35	
ON-state resistance (C connection)			$I_{ON} = 4.0 \text{ A}, I_F = 5 \text{ mA}, t < 1 \text{ s}$	_	11	18	

Note 1: For an application circuit example, see Chapter 12.2.

10. Isolation Characteristics (Unless otherwise specified, Ta = 25 °C)

Characteristics	Symbol	Note	Test Condition	Min	Тур.	Max	Unit
Total capacitance (input to output)	Cs	(Note 1)	V _S = 0 V, f = 1 MHz		0.8		pF
Isolation resistance	R_S	(Note 1)	V _S = 500 V, R.H. ≤ 60 %	5 × 10 ¹⁰	1014		Ω
Isolation voltage	BVS	(Note 1)	AC, 60 s	1500	_	_	Vrms
			AC, 1 s in oil		3000	_	
			DC, 60 s, in oil	_	3000	_	Vdc

Note 1: This device is considered as a two-terminal device: Pins 1, 2 and 3 are shorted together, and pins 4, 5 and 6 are shorted together.



11. Switching Characteristics (Unless otherwise specified, T_a = 25 °C)

Characteristics	Symbol	Note	Test Condition	Min	Тур.	Max	Unit
Turn-on time	t _{ON}		See Fig. 11.1. $R_L = 200 \Omega$, $V_{DD} = 20 V$, $I_F = 5 mA$	_	1.1	5.0	ms
			See Fig. 11.1. $R_L = 200 \Omega$, $V_{DD} = 20 V$, $I_F = 10 mA$	_	0.6	3.0	
Turn-off time	t _{OFF}		See Fig. 11.1. $R_L = 200 \Omega$, $V_{DD} = 20 V$, $I_F = 5 mA$	_	0.1	1.0	
			See Fig. 11.1. $R_L = 200 \Omega$, $V_{DD} = 20 V$, $I_F = 10 mA$	_	0.1	1.0	

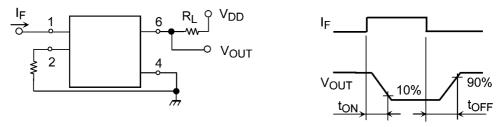


Fig. 11.1 Switching Time Test Circuit and Waveform

12. Characteristics Curves and Circuit Connections

12.1. Characteristics Curves (Note)

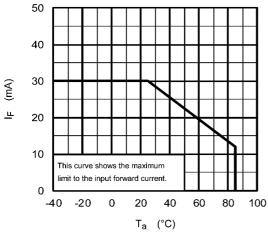


Fig. 12.1.1 I_F - T_a

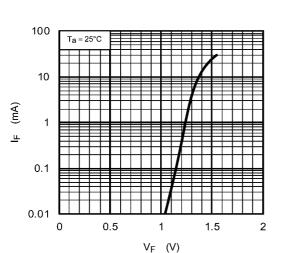


Fig. 12.1.3 I_F - V_F

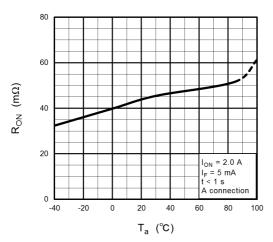


Fig. 12.1.5 R_{ON} - T_a

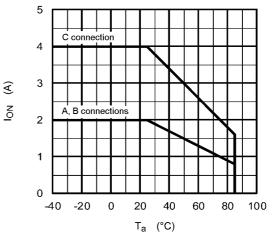


Fig. 12.1.2 I_{ON} - T_a

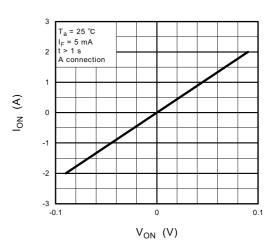


Fig. 12.1.4 I_{ON} - V_{ON}

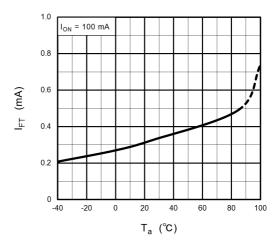
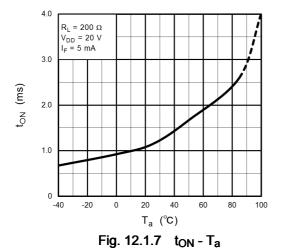
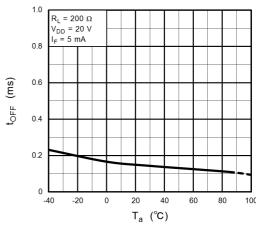


Fig. 12.1.6 I_{FT} - T_a





TLP3109

Fig. 12.1.8 t_{OFF} - T_a

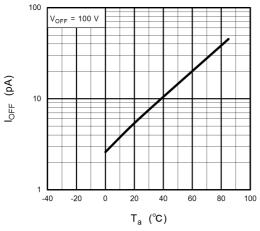


Fig. 12.1.9 I_{OFF} - T_a

Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.



12.2. Circuit Connections

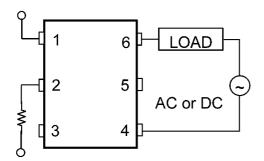


Fig. 12.2.1 A Connection

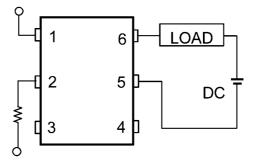


Fig. 12.2.2 B Connection

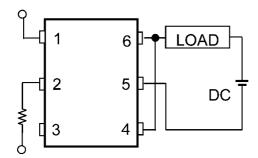
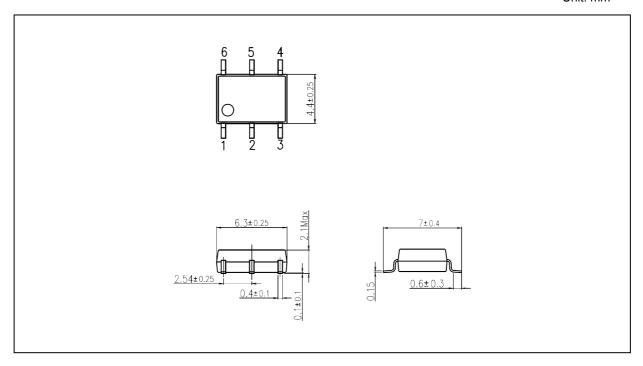


Fig. 12.2.3 C Connection



Package Dimensions

Unit: mm



Weight: 0.13 g (typ.)

	Package Name(s)
TOSHIBA: 11-7C1S	



RESTRICTIONS ON PRODUCT USE

- Toshiba Corporation, and its subsidiaries and affiliates (collectively "TOSHIBA"), reserve the right to make changes to the information in this document, and related hardware, software and systems (collectively "Product") without notice.
- This document and any information herein may not be reproduced without prior written permission from TOSHIBA. Even with TOSHIBA's
 written permission, reproduction is permissible only if reproduction is without alteration/omission.
- Though TOSHIBA works continually to improve Product's quality and reliability, Product can malfunction or fail. Customers are responsible for complying with safety standards and for providing adequate designs and safeguards for their hardware, software and systems which minimize risk and avoid situations in which a malfunction or failure of Product could cause loss of human life, bodily injury or damage to property, including data loss or corruption. Before customers use the Product, create designs including the Product, or incorporate the Product into their own applications, customers must also refer to and comply with (a) the latest versions of all relevant TOSHIBA information, including without limitation, this document, the specifications, the data sheets and application notes for Product and the precautions and conditions set forth in the "TOSHIBA Semiconductor Reliability Handbook" and (b) the instructions for the application with which the Product will be used with or for. Customers are solely responsible for all aspects of their own product design or applications, including but not limited to (a) determining the appropriateness of the use of this Product in such design or applications; (b) evaluating and determining the applicability of any information contained in this document, or in charts, diagrams, programs, algorithms, sample application circuits, or any other referenced documents; and (c) validating all operating parameters for such designs and applications.
 TOSHIBA ASSUMES NO LIABILITY FOR CUSTOMERS' PRODUCT DESIGN OR APPLICATIONS.
- PRODUCT IS NEITHER INTENDED NOR WARRANTED FOR USE IN EQUIPMENTS OR SYSTEMS THAT REQUIRE
 EXTRAORDINARILY HIGH LEVELS OF QUALITY AND/OR RELIABILITY, AND/OR A MALFUNCTION OR FAILURE OF WHICH MAY
 CAUSE LOSS OF HUMAN LIFE, BODILY INJURY, SERIOUS PROPERTY DAMAGE AND/OR SERIOUS PUBLIC IMPACT
 ("UNINTENDED USE"). Except for specific applications as expressly stated in this document, Unintended Use includes, without limitation,
 equipment used in nuclear facilities, equipment used in the aerospace industry, medical equipment, equipment used for automobiles,
 trains, ships and other transportation, traffic signaling equipment, equipment used to control combustions or explosions, safety devices,
 elevators and escalators, devices related to electric power, and equipment used in finance-related fields. IF YOU USE PRODUCT FOR
 UNINTENDED USE, TOSHIBA ASSUMES NO LIABILITY FOR PRODUCT. For details, please contact your TOSHIBA sales
 representative.
- · Do not disassemble, analyze, reverse-engineer, alter, modify, translate or copy Product, whether in whole or in part.
- Product shall not be used for or incorporated into any products or systems whose manufacture, use, or sale is prohibited under any
 applicable laws or regulations.
- The information contained herein is presented only as guidance for Product use. No responsibility is assumed by TOSHIBA for any
 infringement of patents or any other intellectual property rights of third parties that may result from the use of Product. No license to any
 intellectual property right is granted by this document, whether express or implied, by estoppel or otherwise.
- ABSENT A WRITTEN SIGNED AGREEMENT, EXCEPT AS PROVIDED IN THE RELEVANT TERMS AND CONDITIONS OF SALE
 FOR PRODUCT, AND TO THE MAXIMUM EXTENT ALLOWABLE BY LAW, TOSHIBA (1) ASSUMES NO LIABILITY WHATSOEVER,
 INCLUDING WITHOUT LIMITATION, INDIRECT, CONSEQUENTIAL, SPECIAL, OR INCIDENTAL DAMAGES OR LOSS, INCLUDING
 WITHOUT LIMITATION, LOSS OF PROFITS, LOSS OF OPPORTUNITIES, BUSINESS INTERRUPTION AND LOSS OF DATA, AND
 (2) DISCLAIMS ANY AND ALL EXPRESS OR IMPLIED WARRANTIES AND CONDITIONS RELATED TO SALE, USE OF PRODUCT,
 OR INFORMATION, INCLUDING WARRANTIES OR CONDITIONS OF MERCHANTABILITY, FITNESS FOR A PARTICULAR
 PURPOSE, ACCURACY OF INFORMATION, OR NONINFRINGEMENT.
- GaAs (Gallium Arsenide) is used in Product. GaAs is harmful to humans if consumed or absorbed, whether in the form of dust or vapor.
 Handle with care and do not break, cut, crush, grind, dissolve chemically or otherwise expose GaAs in Product.
- Do not use or otherwise make available Product or related software or technology for any military purposes, including without limitation, for the design, development, use, stockpiling or manufacturing of nuclear, chemical, or biological weapons or missile technology products (mass destruction weapons). Product and related software and technology may be controlled under the applicable export laws and regulations including, without limitation, the Japanese Foreign Exchange and Foreign Trade Law and the U.S. Export Administration Regulations. Export and re-export of Product or related software or technology are strictly prohibited except in compliance with all applicable export laws and regulations.
- Please contact your TOSHIBA sales representative for details as to environmental matters such as the RoHS compatibility of Product.
 Please use Product in compliance with all applicable laws and regulations that regulate the inclusion or use of controlled substances, including without limitation, the EU RoHS Directive. TOSHIBA ASSUMES NO LIABILITY FOR DAMAGES OR LOSSES OCCURRING AS A RESULT OF NONCOMPLIANCE WITH APPLICABLE LAWS AND REGULATIONS.

X-ON Electronics

Largest Supplier of Electrical and Electronic Components

Click to view similar products for Solid State Relays - PCB Mount category:

Click to view products by Toshiba manufacturer:

Other Similar products are found below:

M86F-2W M90F-2W G2-1A07-ST G2-1A07-TT G2-1B02-TT G2-DA06-ST G3CN-202PL-3-US DC12 G3CN-203P DC3-28

G3RDX02SNUSDC12 PLA134S DMP6202A DS11-1005 AQ3A2-ZT432VDC AQV212J AQV214SD02 AQV252GAJ AQW414EA

AQY212SXT AQY221N2SJ AQY221R2SJ EFR1200480A150 LCA220 LCB110S 1618400-5 SR75-1ST AQV212AJ AQV238AD01

AQV252GAXJ AQW414TS AQY210SXT AQY212ST AQY214SXT AQY221N2V1YJ AQY275AXJ G2-1A02-ST G2-1A02-TT G2
1A03-ST G2-1A03-TT G2-1A05-ST G2-1A06-TT G2-1A23-TT G2-1B01-ST G2-1B01-TT G2-1B02-ST G2-DA03-ST G2-DA03-TT G2
DA06-TT G3M-203PL-UTU-1 DC24 CPC2330N 3-1617776-2